

● General Description

The AGMH022N10C combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

This device is ideal for load switch and battery protection applications.

● Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- 100% Avalanche tested
- 100% DVDS tested

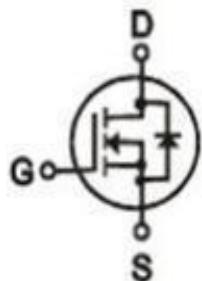
● Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

Product Summary

BVDSS	RDS(on)	ID
100V	2.2mΩ	220A

TO-220 Pin Configuration



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGMH022N10C	AGMH022N10C	TO-220	---	---	1000

Table 1. Absolute Maximum Ratings (TC=25°C)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	100	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Tc=25°C) (Note 1)	220	A
	Drain Current-Continuous(Tc=100°C)	132	A
IDM (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 2)	880	A
PD	Maximum Power Dissipation(Tc=25°C)	300	W
	Maximum Power Dissipation(Tc=100°C)	150	W
EAS	Avalanche energy (Note 3)	1800	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 175	°C

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
R _{θJC}	Thermal Resistance Junction-Case ¹	---	0.5	°C/W

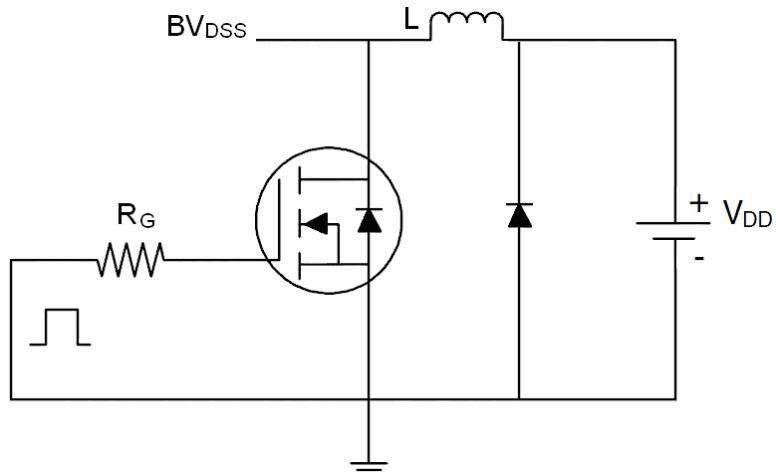
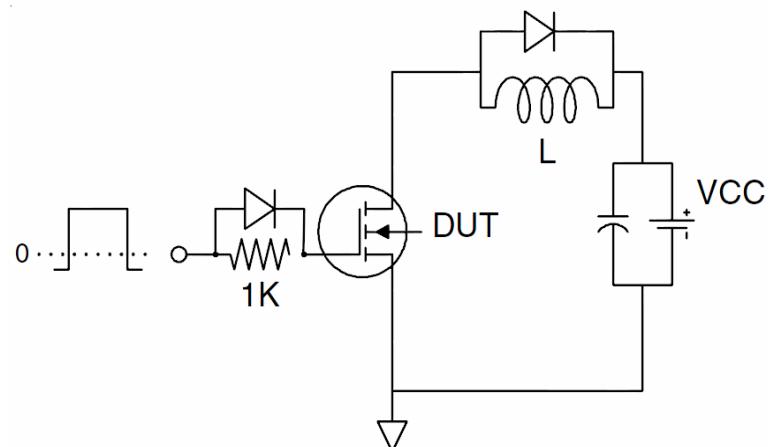
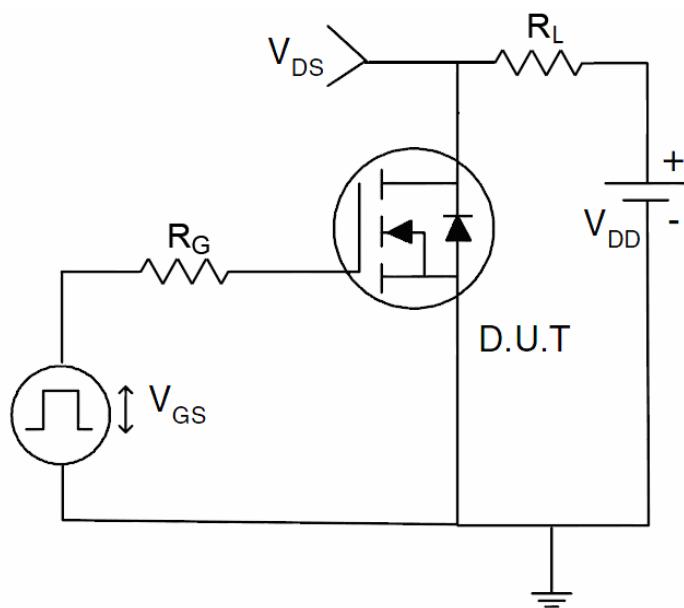
Table 3. Electrical Characteristics (TC=25°C unless otherwise noted)

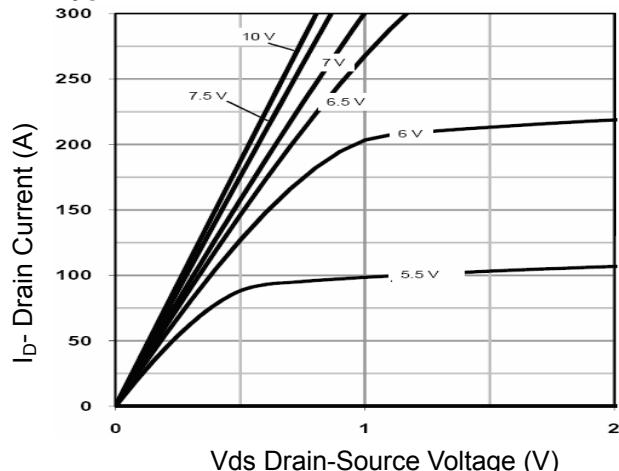
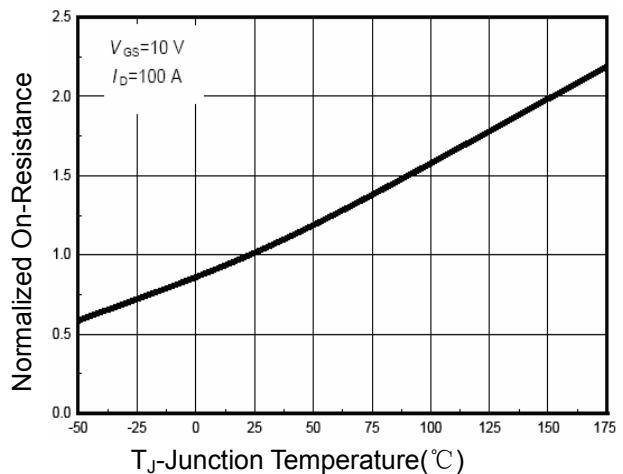
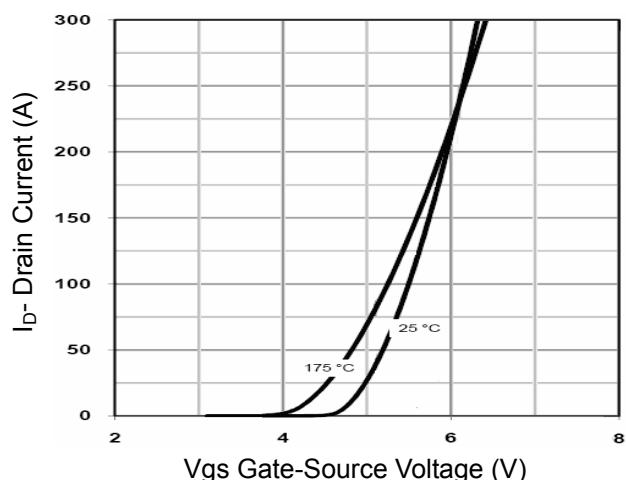
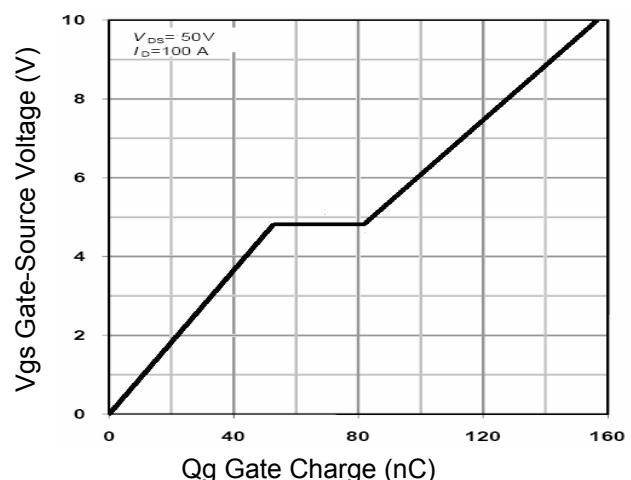
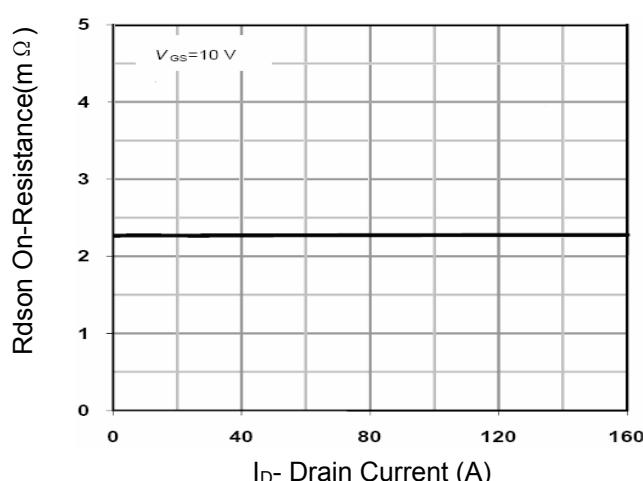
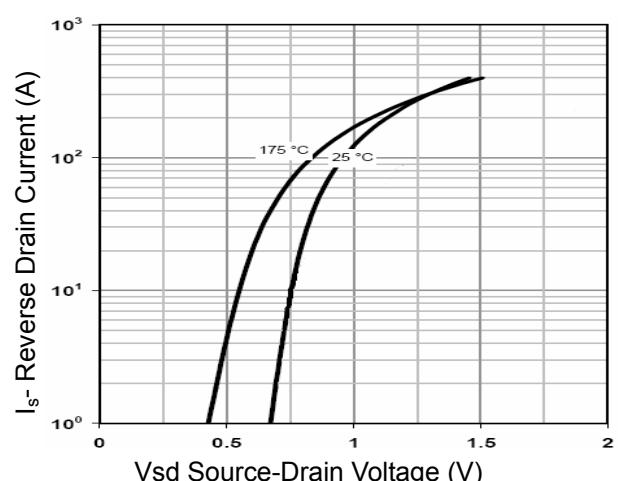
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250μA	100	--	--	V
IDSS	Zero Gate Voltage Drain Current	VDS=100V, VGS=0V	--	--	1	μA
IGSS	Gate-Body Leakage Current	VGS=±20V, VDS=0V	--	--	±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS, ID=250μA	2.5	3.5	4.5	V
gFS	Forward Transconductance	VDS=5V, ID=10A	--	35	--	S
RDS(on)	Drain-Source On-State Resistance	VGS=10V, ID=50A	--	2.2	2.85	mΩ
Dynamic Characteristics						
Ciss	Input Capacitance	VDS=50V, VGS=0V, F=1MHZ	--	11500	--	pF
Coss	Output Capacitance		--	1480	--	pF
Crss	Reverse Transfer Capacitance		--	75	--	pF
Switching Times						
td(on)	Turn-on Delay Time	VGS=10V, VDS=50V, ID=100A, RGEN=1.6Ω	--	25	--	nS
tr	Turn-on Rise Time		--	75	--	nS
td(off)	Turn-Off Delay Time		--	89	--	nS
tf	Turn-Off Fall Time		--	29	--	nS
Qg	Total Gate Charge	VGS=10V, VDS=50V, ID=100A	--	158	--	nC
Qgs	Gate-Source Charge		--	52	--	nC
Qgd	Gate-Drain Charge		--	29	--	nC
Source-Drain Diode Characteristics						
ISD	Source-Drain Current(Body Diode)		--	--	220	A
VSD	Forward on Voltage	VGS=0V, IS=20A	--	--	1.2	V
trr	Reverse Recovery Time	IF=20A, dI/dt=100A/μs, TJ=25°C	--	75	--	ns
Qrr	Reverse Recovery Charge		--	185	--	nc

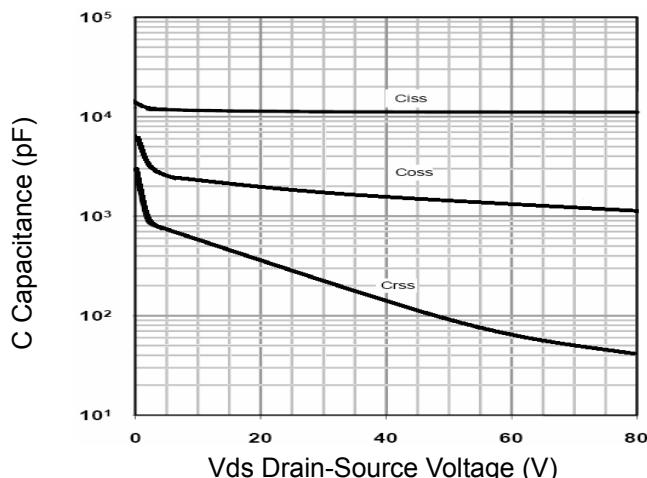
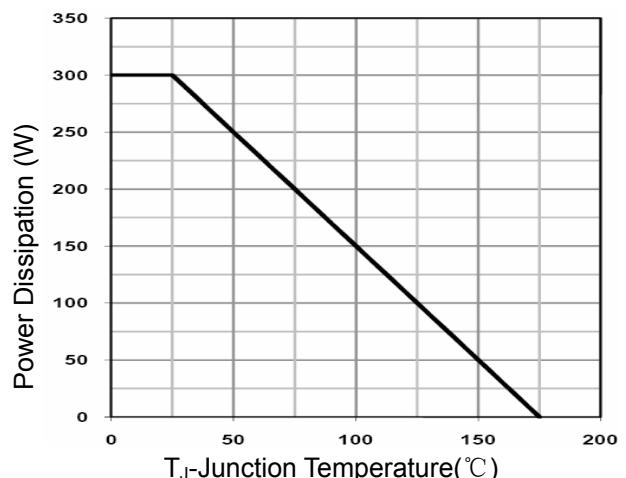
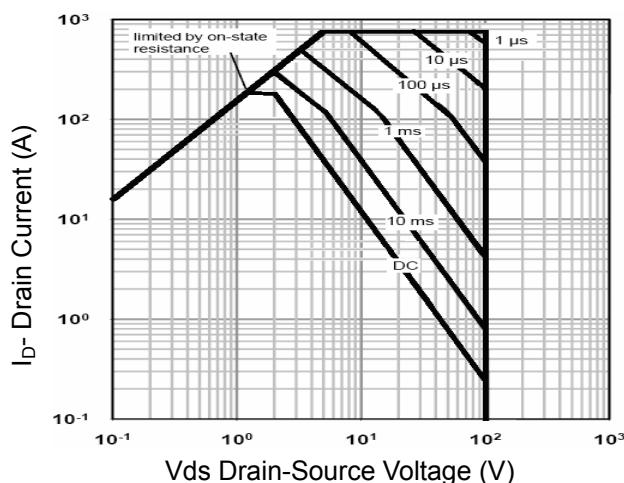
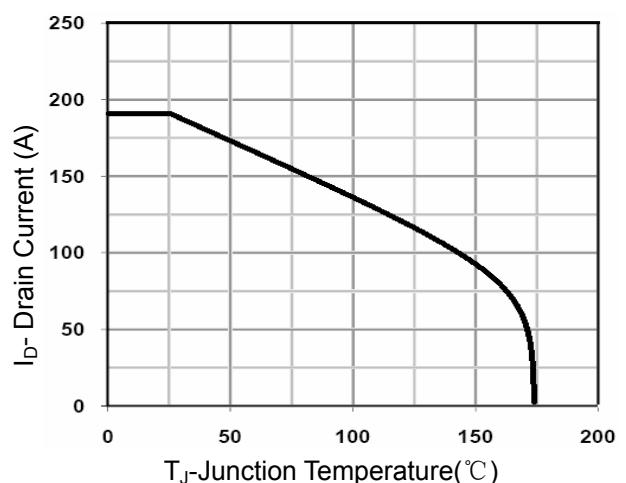
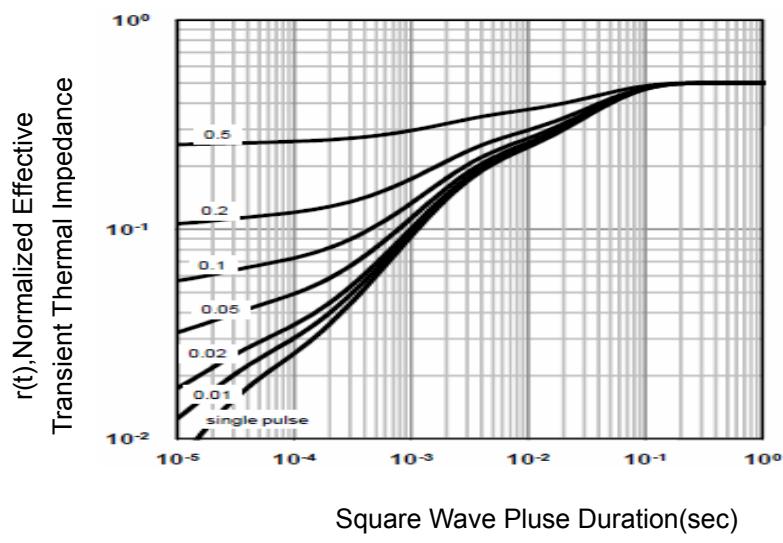
Notes 1.The maximum current rating is package limited.

Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

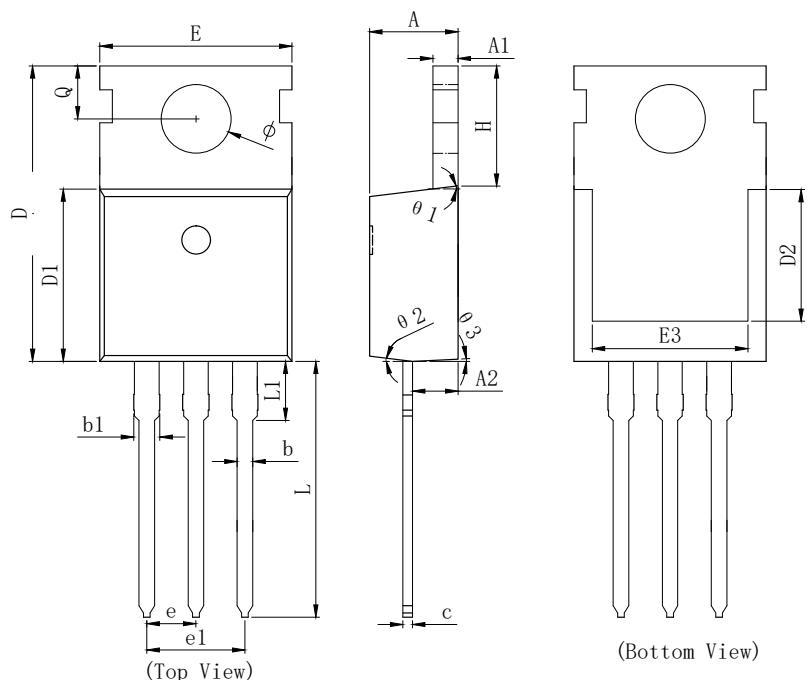
Notes 3.EAS condition: TJ=25°C

Test Circuit**1) E_{AS} test Circuit****2) Gate charge test Circuit****3) Switch Time Test Circuit**

Typical Electrical and Thermal Characteristics**Figure 1 Output Characteristics****Figure 4 Rdson-Junction Temperature****Figure 2 Transfer Characteristics****Figure 5 Gate Charge****Figure 3 Rdson- Drain Current****Figure 6 Source- Drain Diode Forward**

**Figure 7 Capacitance vs Vds****Figure 9 Power De-rating****Figure 8 Safe Operation Area****Figure 10 Current De-rating****Figure 11 Normalized Maximum Transient Thermal Impedance**

TO220 PACKAGE INFORMATION



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	4.370	4.570	4.700
A1	1.250	1.300	1.400
A2	2.150	2.350	2.550
b	0.700	0.800	0.950
b1	1.170	1.270	1.470
c	0.450	0.500	0.600
D	15.100	15.600	16.100
D1	8.800	9.100	9.400
D2	5.500	6.300 REF	
E	9.700	10.000	10.300
E3	7.000	7.600 REF	
e	2.540 BSC		
e1	5.080 BSC		
L	13.200	13.500	13.800
L1		3.100	3.400
H	6.250	6.500	6.750
Φ	3.400	3.600	3.800
Q	2.600	2.800	3.000
θ 1	7° TYP		
θ 2	7° TYP		
θ 3	3° TYP		

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